

REMARKS

Claims 1-39 were originally pending in the parent application Serial No. 09/285,621. In view of the restriction requirement in the parent case, Applicants herein have canceled claims 1-19, 28, 29, and 34-39 and have elected claims 20-27 and 30-33 for examination in this case. Applicants have also taken this opportunity to amend the specification in keeping with amendment to the specification made in the parent case. Entry and consideration of the foregoing amendments are respectfully requested.

If there are any questions regarding this application, the undersigned requests an opportunity to discuss this case with the Examiner either in person or by telephone interview.

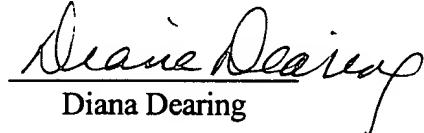
Respectfully submitted,
Intellectual Property Group of
PILLSBURY WINTHROP LLP

By 
Christopher D. Agnew
Registered Patent Agent
Reg. No. 43,464
Tel. No.: (650) 233-4609
Fax No.: (650) 233-4040

Pillsbury Winthrop LLP
1600 Tysons Boulevard
McLean, Virginia 22102

CERTIFICATE OF MAILING (37 CFR 1.8a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service, postage prepaid, to the Asst. Commissioner for Patents, Washington D.C. 20231, this 8th day of November, 2001.


Diana Dearing

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Page 8, first full paragraph starting on line 10:

Instead of using the cathode contacts 38 described above, the electric potential can be applied to the wafer using a ring conductor. Further, other methods of applying the electric potential to the wafer may be used in accordance with the present invention. For example, a liquid conductor or an inflatable tube coated with a conductive material may be used in the present invention. An example of using the liquid conductor or the conductive tube to provide the necessary electric potential according to the present invention is disclosed in the co-pending U.S. Application Serial No. 09/283,024, filed March 30, 1999 [_____], Atty. Dkt. # 42496/0253036], entitled "Method And Apparatus For Forming An Electric Contact With A Semiconductor Substrate", commonly owned by the assignee of the present invention, the contents of which are expressly incorporated herein by reference.

IN THE CLAIMS:

Claims 1-19, 28, 29, and 34-39 are canceled.